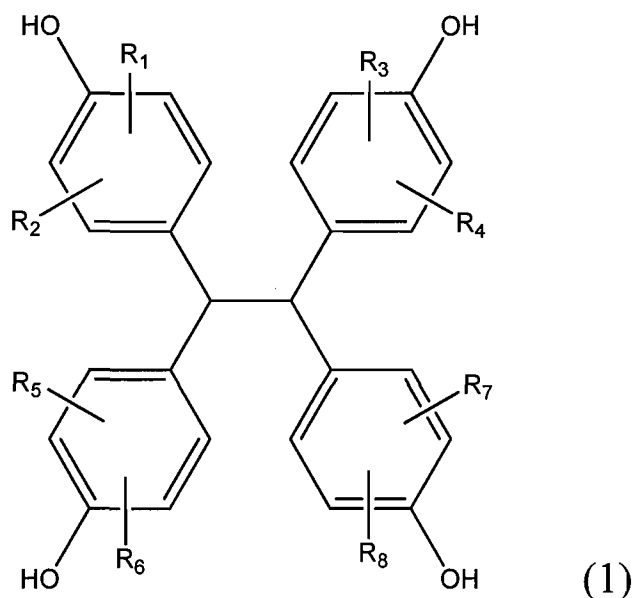


AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior versions, and listings, of claims in this application.

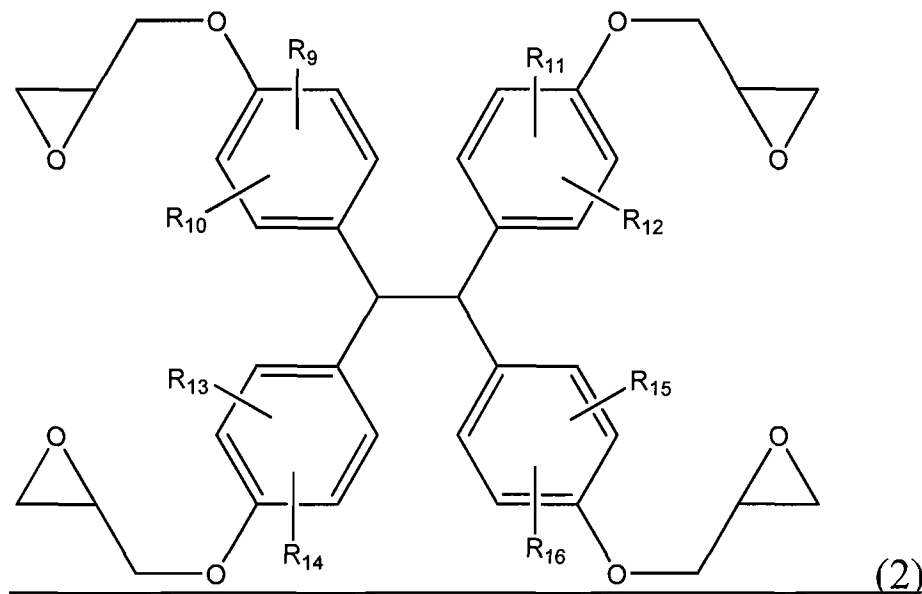
Claim 1 (**Currently Amended**): A photosensitive resin composition comprising a resin (A) soluble in an aqueous alkaline solution, a crosslinking agent (B), a photopolymerization initiator (C), and a curing agent (D), ~~wherein~~wherein:

the curing agent (D) is an epoxy compound obtained by glycidylating a compound containing not less than ~~[[80%]]~~80 area% as measured by high performance liquid chromatography at UV 254 nm of a tetraphenylethane derivative represented by formula (1):



wherein R₁ to R₈ each independently represents a hydrogen atom, ~~a C₁-to-C₄-alkyl group, or a halogen atom.~~atom;

the curing agent (D) includes a compound represented by formula (2):



wherein R₉ to R₁₆ each independently represents a hydrogen atom, and the content of the compound in the curing agent (D) is not less than 60 mole percent; and

the curing agent (D) has an epoxy equivalent of 155 to 180 g/equivalent and a light transmittance at 400 nm of not less than 10% in a 1 weight percent methyl ethyl ketone solution.

Claims 2 and 3 (**Canceled**).

Claim 4 (**Previously Presented**): The photosensitive resin composition according to claim 1, wherein the curing agent (D) has a softening point or melting point of not less than 80°C.

Claim 5 (**Canceled**).

Claim 6 (**Previously Presented**): The photosensitive resin composition according to claim 1, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (a) having two or more epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, and a polybasic acid anhydride (c).

Claim 7 (**Previously Presented**): The photosensitive resin composition according to claim 1, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (d) having two epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, a diisocyanate compound (e), a carboxylic acid (f) having two hydroxyl groups per molecule, and, as an optional component, a diol compound (g).

Claim 8 (**Previously Presented**): A cured product of the photosensitive resin composition according to claim 1.

Claim 9 (**Original**): A substrate comprising a layer composed of the cured product according to claim 8.

Claim 10 (**Original**): An article comprising the substrate according to claim 9.

Claims 11-24 (**Canceled**).